Celanese
The chemistry inside innovation™

ZENITE® 350 LDS

This LCP is designed for Laser Direct Structuring, low dielectric constant, and low dissipation factor

Rheological properties

Moulding shrinkage range, parallel	0.2	%	ISO 294-4, 2577
Moulding shrinkage range, normal	0.9	%	ISO 294-4, 2577

Typical mechanical properties

Tensile Modulus	11000	MPa	ISO 527-1/-2
Stress at break, 5mm/min	134	MPa	ISO 527-1/-2
Strain at break, 5mm/min	3.1	%	ISO 527-1/-2
Flexural Modulus	10000	MPa	ISO 178
Flexural Strength	158	MPa	ISO 178
Charpy impact strength, 23°C	51	kJ/m²	ISO 179/1eU

Thermal properties

Temp. of deflection under load, 1.8 MPa	240	°C	ISO 75-1/-2

Flammability

Burning Behav. at thickness h	V-0	class	UL 94
Thickness tested	0.4	mm	UL 94
UL recognition	yes		UL 94

Electrical properties

Relative permittivity, 2GHz	3.7	E-4	IEC 62631-2-1
Dissipation factor, printed circuits and boards, 2.5 GHz	60	E-4	IEC 61189-2-721

Injection

Drying Temperature	150	°C
Drying Time, Dehumidified Dryer	6	h
Max. mould temperature	100	°C
Injection speed	medium-fast	

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